

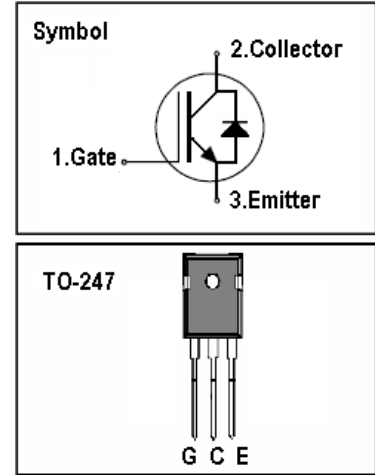
## IGBT

### Features

- 1200V,30A, $V_{CE(sat)(typ.)}=2.1V@V_{GE}=15V$
- High speed switching
- Higher system efficiency
- Soft current turn-off waveforms
- Square RBSOA

### General Description

H&M IGBTs offer lower losses and higher energy efficiency for application such as Motor driver, UPS, General inverter and other soft switching applications.



### Absolute Maximum Ratings

Symbol	Parameter	Value	Units
$V_{CES}$	Collector-Emitter Voltage	1200	V
$V_{GES}$	Gate-Emitter Voltage	$\pm 30$	V
$I_C$	Continuous Collector Current ( $T_C=25^\circ C$ )	55	A
	Continuous Collector Current ( $T_C=100^\circ C$ )	28	A
$I_{CM}$	Pulsed Collector Current (Note 1)	240	A
$I_F$	Diode Continuous Forward Current ( $T_C=100^\circ C$ )	25	A
$I_{FM}$	Diode Maximum Forward Current (Note 1)	240	A
$P_D$	Maximum Power Dissipation ( $T_C=25^\circ C$ )	300	W
	Maximum Power Dissipation ( $T_C=100^\circ C$ )	120	W
TSC	Short circuit withstand time	10	us
$T_J$	Operating Junction Temperature Range	-55 to +150	$^\circ C$
$T_{STG}$	Storage Temperature Range	-55 to +150	$^\circ C$

### Thermal Characteristics

Symbol	Parameter	Max.	Units
$R_{thj-c}$	Thermal Resistance, Junction to case for IGBT	0.42	$^\circ C / W$
$R_{thj-cd}$	Thermal Resistance, Junction to case for Diode	0.83	$^\circ C / W$
$R_{thj-a}$	Thermal Resistance, Junction to Ambient	40	$^\circ C / W$

**Electrical Characteristics** ( $T_C=25^\circ\text{C}$  unless otherwise noted )

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$BV_{CES}$	Collector-Emitter Breakdown Voltage	$V_{GE}=0V, I_C=250\mu A$	1200	-	-	V
$I_{CES}$	Collector-Emitter Leakage Current	$V_{CE}=1200V, V_{GE}=0V$	-	-	250	$\mu A$
$I_{GES}$	Gate Leakage Current, Forward	$V_{GE}=30V, V_{CE}=0V$	-	-	100	nA
	Gate Leakage Current, Reverse	$V_{GE}=-30V, V_{CE}=0V$	-	-	-100	nA
$V_{GE(th)}$	Gate Threshold Voltage	$V_{GE}=V_{CE}, I_C=250\mu A$	4.0	5.0	6.0	V
$V_{CE(sat)}$	Collector-Emitter Saturation Voltage	$V_{GE}=15V, I_C=30A$	-	2.1	2.3	V
$Q_g$	Total Gate Charge	$V_{CC}=960V$ $V_{GE}=15V$ $I_C=30A$	-	178	-	nC
$Q_{ge}$	Gate-Emitter Charge		-	36	-	nC
$Q_{gc}$	Gate-Collector Charge		-	84	-	nC
$t_{d(on)}$	Turn-on Delay Time	$V_{CC}=600V$ $V_{GE}=0V/15V$ $I_C=30A$ $R_G=28\Omega$ Inductive Load $T_C=25^\circ\text{C}$	-	54	-	ns
$t_r$	Turn-on Rise Time		-	72	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	671	-	ns
$t_f$	Turn-off Fall Time		-	44	-	ns
$E_{on}$	Turn-on Switching Loss		-	2.9	-	mJ
$E_{off}$	Turn-off Switching Loss		-	2.2	-	mJ
$E_{ts}$	Total Switching Loss		-	5.1	-	mJ
$C_{ies}$	Input Capacitance	$V_{CE}=30V$ $V_{GE}=0V$ $f=100\text{kHz}$	-	645	-	pF
$C_{oes}$	Output Capacitance		-	206	-	pF
$C_{res}$	Reverse Transfer Capacitance		-	115	-	pF
$R_{gint}$	Integrated gate resistor			2.1		$\Omega$

**Electrical Characteristics of Diode** ( $T_C=25^\circ\text{C}$  unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$V_F$	Diode Forward Voltage	$I_F=30A$	-	2.0	2.2	V
$t_{rr}$	Diode Reverse Recovery Time	$V_{CE}=600V$ $I_F=30A$	-	197	-	ns
$I_{rr}$	Diode peak Reverse Recovery Current		-	20	-	A
$Q_{rr}$	Diode Reverse Recovery Charge	$di_F/dt=500A/\mu s$	-	1923	-	nC

**Notes:**

1. Repetitive Rating: Pulse width limited by maximum junction temperature

## Typical Performance Characteristics

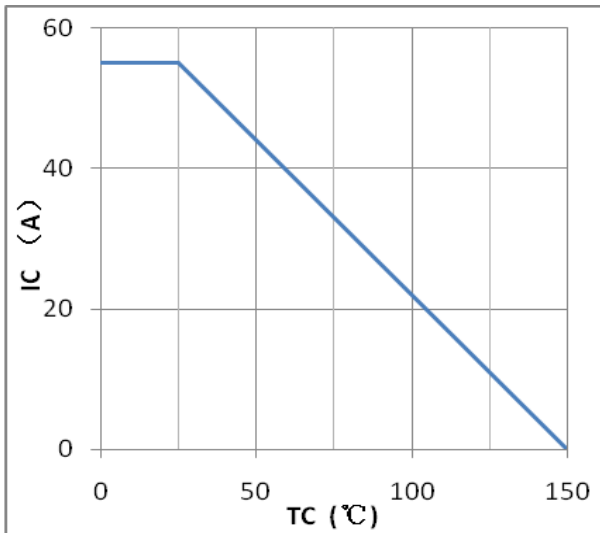


Figure1:maximum DC collector current VS. case temperature

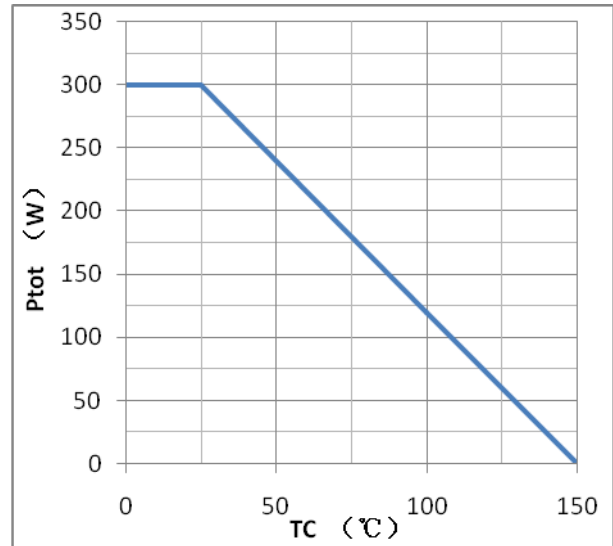


Figure2:power dissipation VS. case temperature

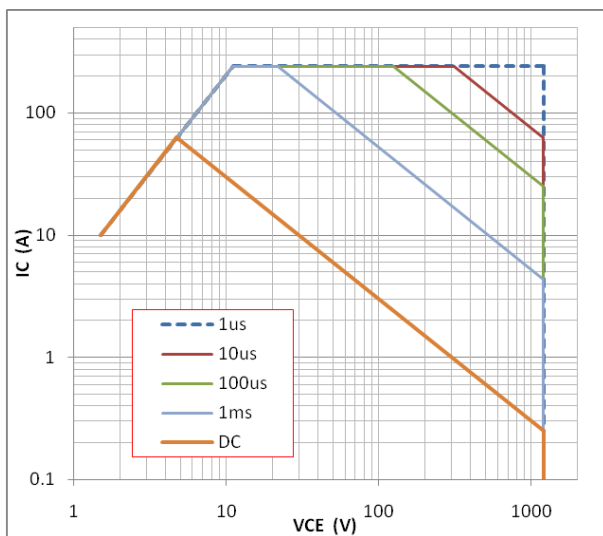


Figure3:forward SOA,TC=25°C,TJ ≤ 150°C

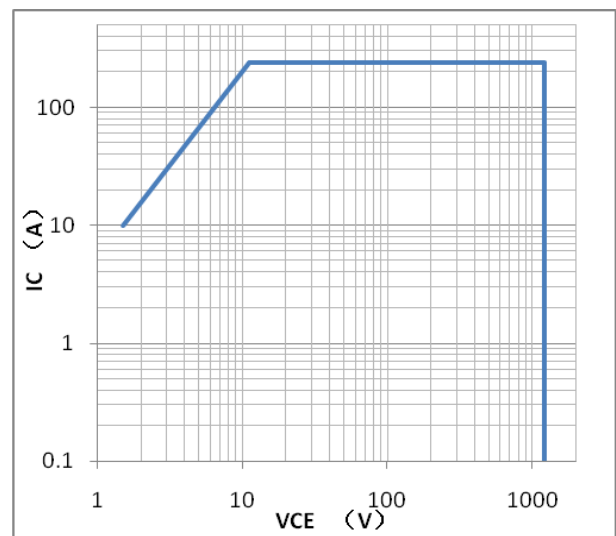


Figure4:reverse bias SOA,TJ=150°C,VGE=15V

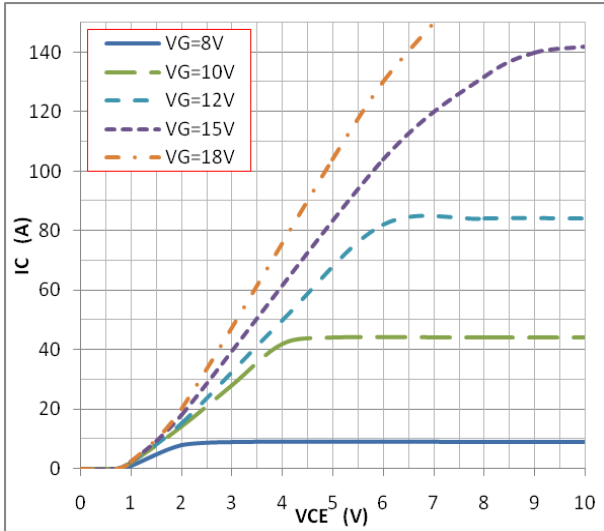


Figure5:typical IGBT output characteristics,  
TJ=25°C;tp=300us

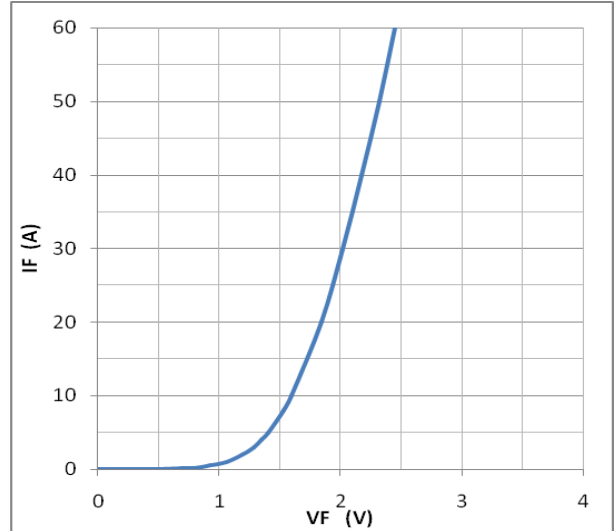


Figure6:typical trans characteristics,VCE=20V,tp=20us

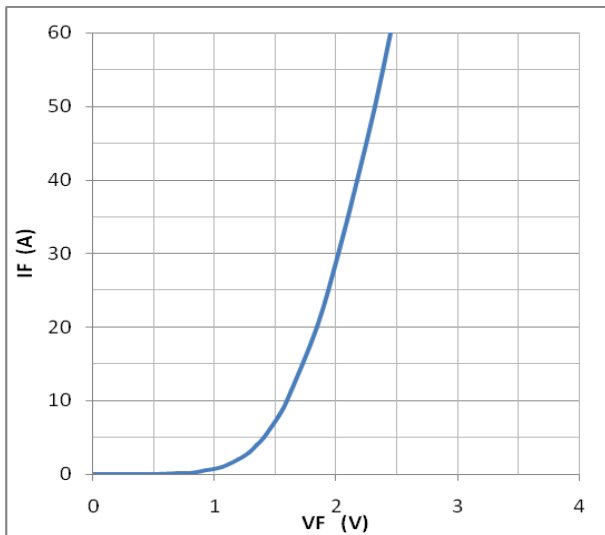


Figure7:typical diode forward characteristic,tp=300us

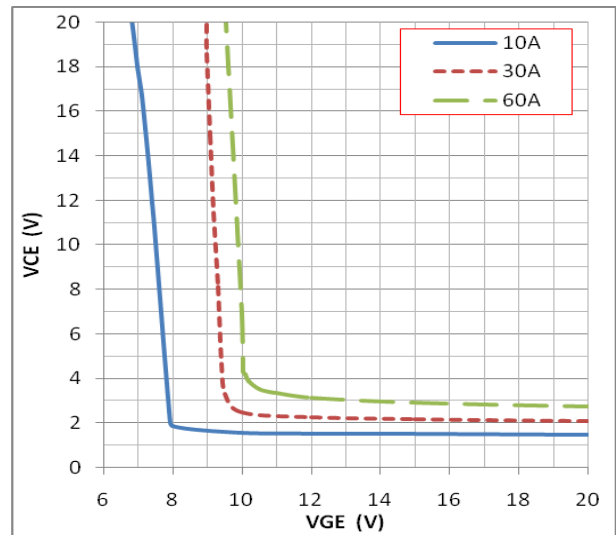


Figure8:typical VCE VS. VGE,TJ=25°C

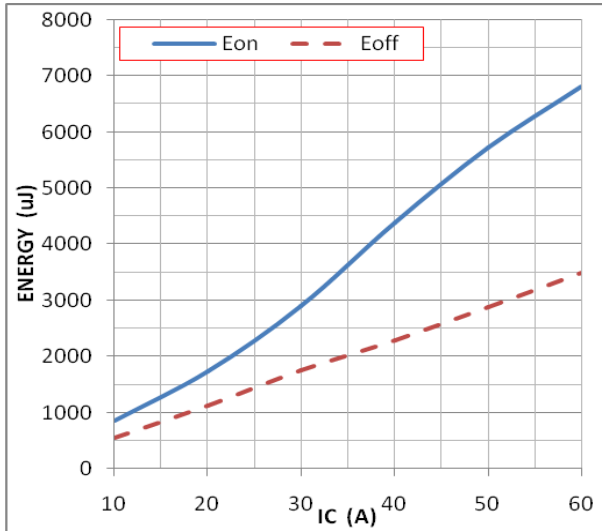


Figure 9: typical energy loss VS. IC, TC=25°C, L=500uH,  
VCE=600V, VGE=15V, Rg=28Ω

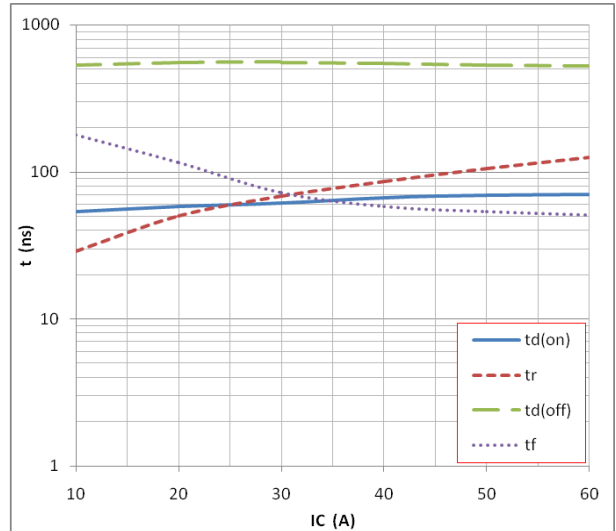


Figure 10: typical switching time VS. IC, TC=25°C,  
L=500uH, VCE=600V, VGE=15V, Rg=28Ω

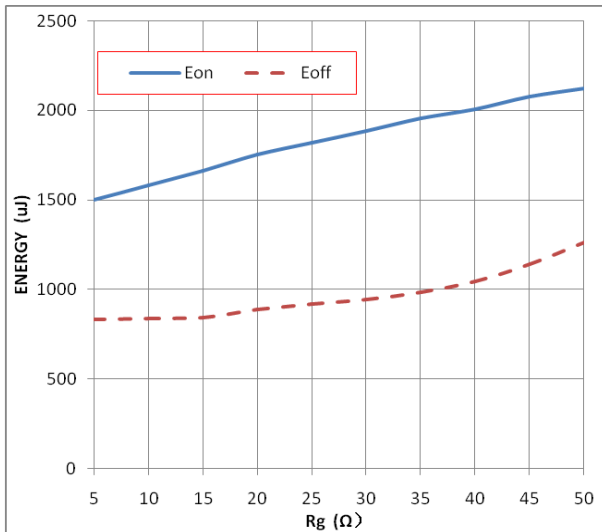


Figure 11: typical energy loss VS. Rg, TC=25°C,  
L=500uH, VCE=600V, VGE=15V, IC=30A

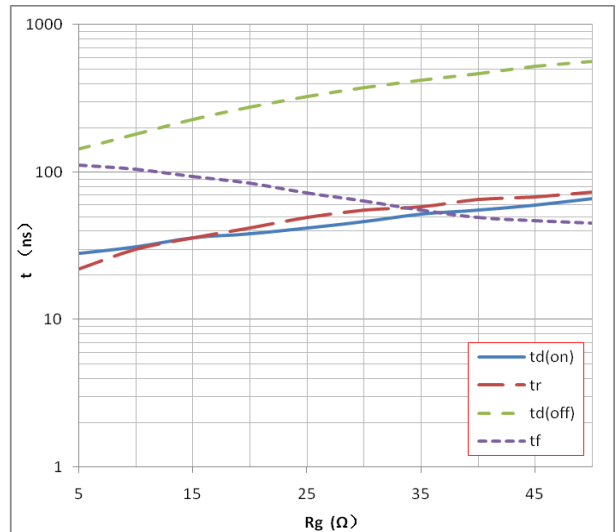


Figure 12: typical switching time VS. Rg, TC=25°C,  
L=500uH, VCE=600V, VGE=15V, IC=30A

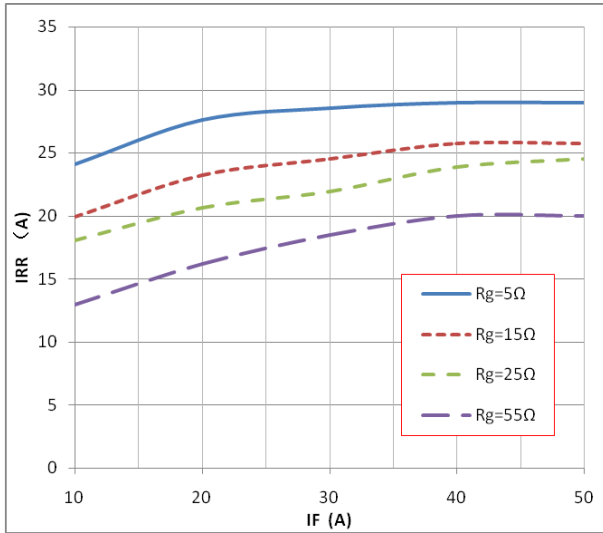


Figure13: typical diode IRR VS. IF, TC=25°C

VCC=600V,VGE=15V

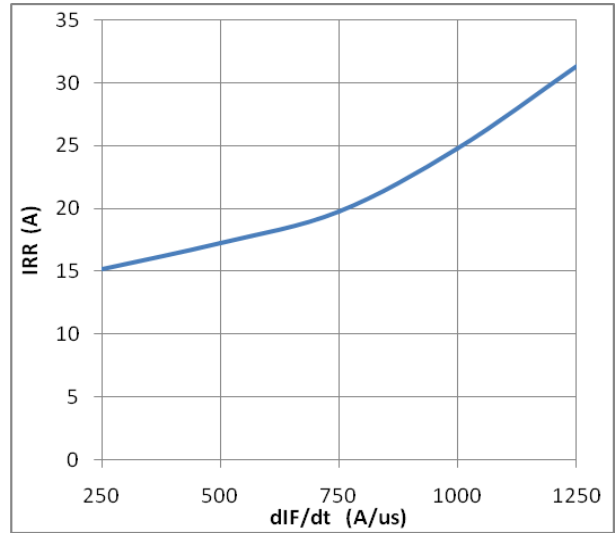


Figure14: typical diode IRR VS. dIF/dt

VCC=600V,VGE=15V,IF=30A

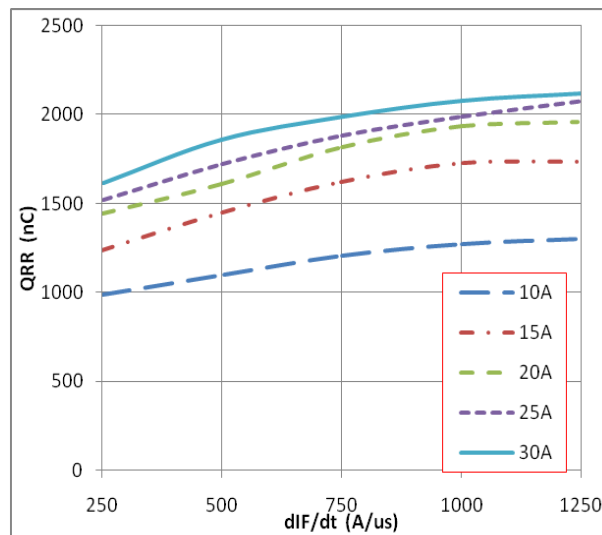


Figure15: typical diode QRR VS. dIF/dt, VCC=600V, VGE=15V

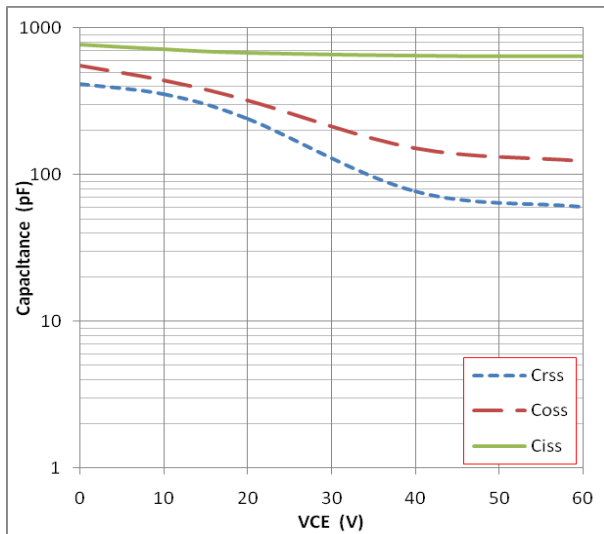


Figure16:typical capacitance VS. VCE,VGE=0V,f=100kHz

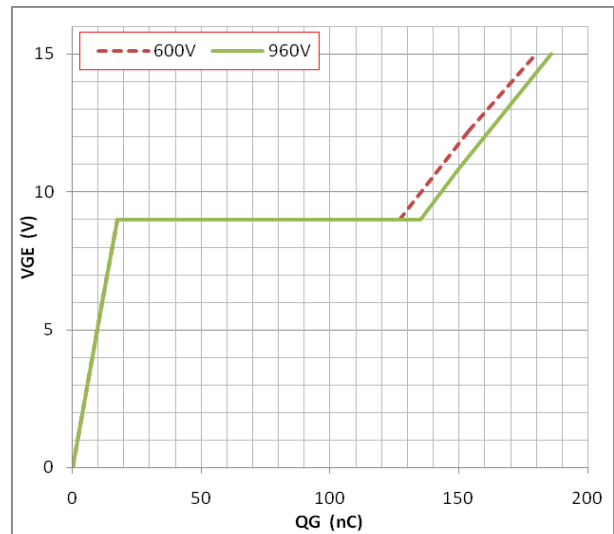


Figure17:typical gate charge VS. VGE,IC=30A

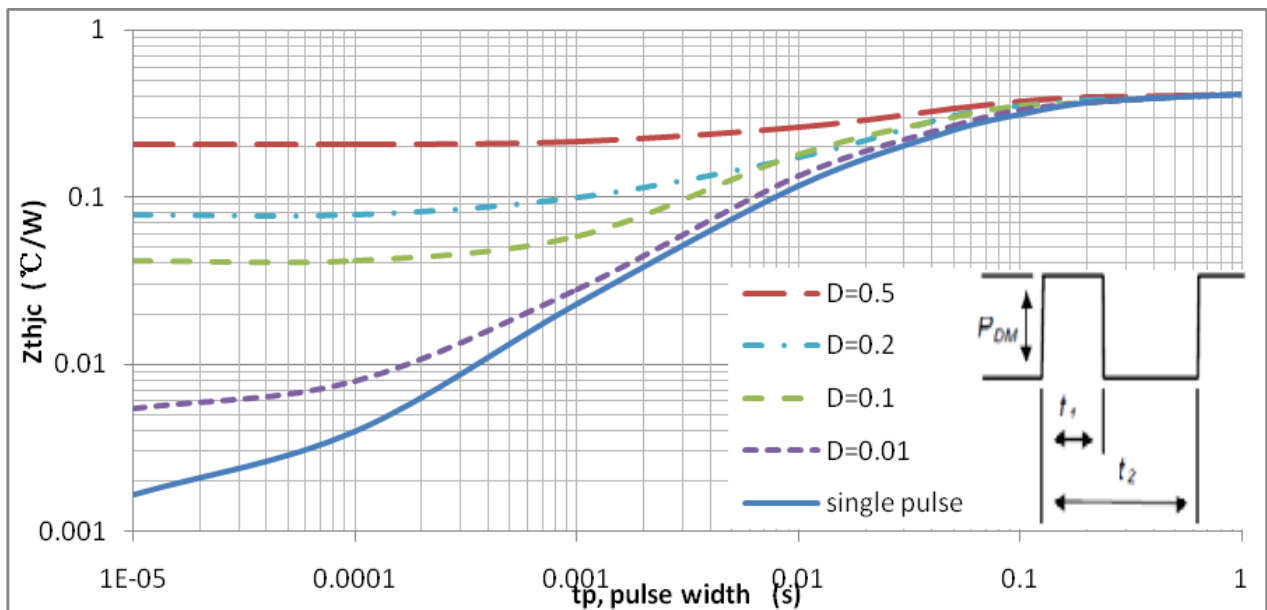
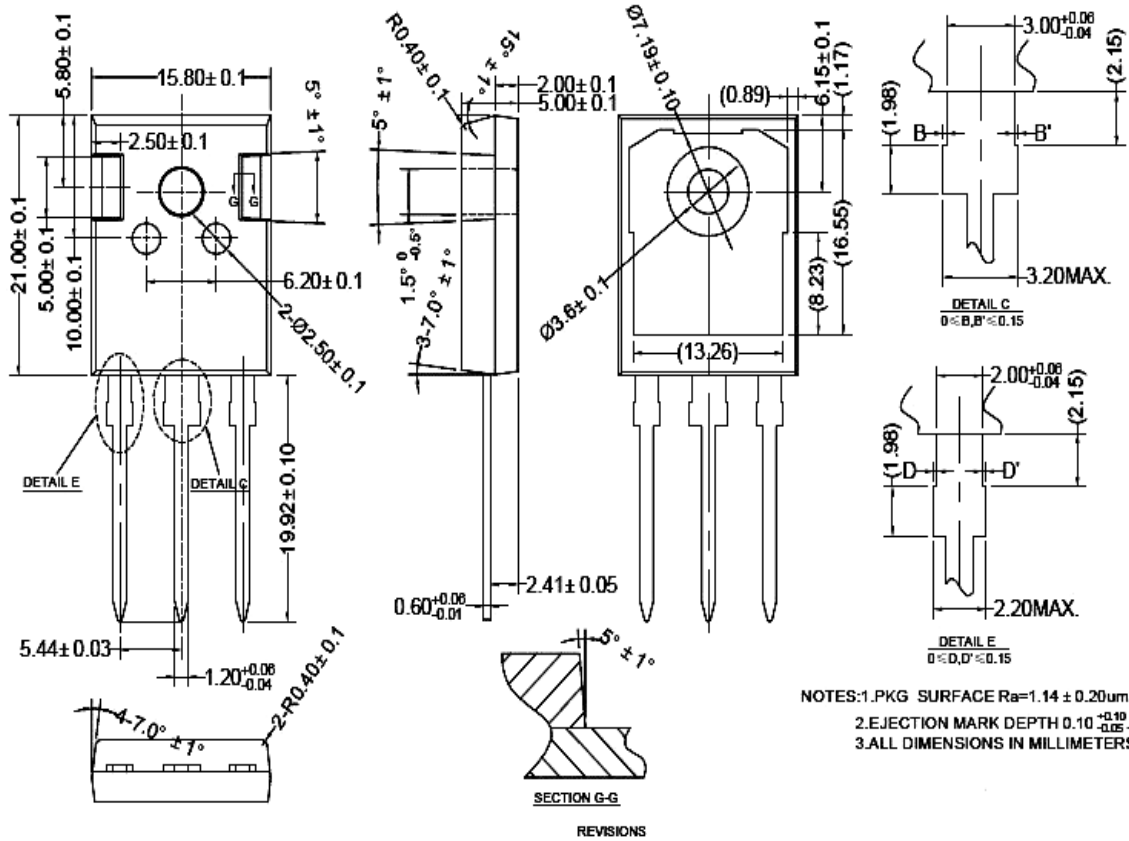


Figure18:normalised transient thermal impedance,junction-to-case

Note1.Duty factor  $D=t_1/t_2$ ;

Note2:peak  $T_J=P_{DM} \times Z_{thjc}+T_C$

TO247 PACKAGE OUTLINE



NOTES:1.PKG SURFACE Ra=1.14 ± 0.20um.  
2.EJECTION MARK DEPTH 0.10 <sup>+0.10</sup>/<sub>-0.05</sub>  
3.ALL DIMENSIONS IN MILLIMETERS.

0 ≤ D, D' ≤ 0.15

NOTES:1.PKG SURFACE Ra=1.14 ± 0.20um.  
2.EJECTION MARK DEPTH 0.10 <sup>+0.10</sup>/<sub>-0.05</sub>  
3.ALL DIMENSIONS IN MILLIMETERS.

公差标注	公差值	表面粗糙度
0	±0.2	Ra3.2~6.3
0.0	±0.1	Ra1.6~3.2
0.00	±0.01	Ra0.8~1.6
0.000	±0.005	Ra0.4~0.8
0.0000	±0.002	Ra0.2~0.4



---

## **Disclaimers**

H&M Semiconductor Co., Ltd reserves the right to make changes without notice in order to improve reliability, function or design and to discontinue any product or service without notice. Customers should obtain the latest relevant information before orders and should verify that such information is current and complete. All products are sold subject to H&M's terms and conditions supplied at the time of order acknowledgement.

H&M Semiconductor Co., Ltd warrants performance of its hardware products to the specifications at the time of sale, Testing, reliability and quality control are used to the extent H&M deems necessary to support this warrantee. Except where agreed upon by contractual agreement, testing of all parameters of each product is not necessarily performed.

H&M Semiconductor Co., Ltd does not assume any liability arising from the use of any product or circuit designs described herein. Customers are responsible for their products and applications using H&M's components. To minimize risk, customers must provide adequate design and operating safeguards.

H&M Semiconductor Co., Ltd does not warrant or convey any license either expressed or implied under its parent rights, nor the rights of others. Reproduction of information in H&M's datasheets or data books is permissible only if reproduction is without modification or alteration. Reproduction of this information with any alteration is an unfair and deceptive business practice. H&M Semiconductor Co., Ltd is not responsible or liable for such altered documentation.

Resale of H&M's products with statements different from or beyond the parameters stated by H&M Semiconductor Co., Ltd for that product or service voids all express or implied warranties for the associated H&M's product or service and is unfair and deceptive business practice. H&M Semiconductor Co., Ltd is not responsible or liable for any such statements.